L	Hits	Search Text	DB	Time stamp
Number -	51211		USPAT;	2003/10/24
		spreader) with substrate) and (chip or die or chips or dies)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	13:12
-	15634	(((metal or metallic or copper or sink or spreader) with substrate) and (chip or die or chips or dies)) and (dice or singulate or singulating or cut or saw)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24
	9376	<pre>((((metal or metallic or copper or sink or spreader) with substrate) and (chip or die or chips or dies)) and (dice or singulate or singulating or cut or saw)) and (dielectric or insulate or insulating)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:14
_	10517	((metal or metallic or copper or sink or spreader) near substrate) and (chip or die or chips or dies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 12:10
-	3581	spreader) near substrate) and (chip or die or chips or dies)) and (dice or singulate or singulating or cut or saw)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24
-	2021	<pre>((((metal or metallic or copper or sink or spreader) near substrate) and (chip or die or chips or dies)) and (dice or singulate or singulating or cut or saw)) and (dielectric or insulate or insulating)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:02
-	1721	<pre>(((((metal or metallic or copper or sink or spreader) near substrate) and (chip or die or chips or dies)) and (dice or singulate or singulating or cut or saw)) and (dielectric or insulate or insulating)) and (@ad<20011231)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24
-	1008		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 12:59
-	148	copper or cu or sink or spreader) near substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:04
-	27	copper or cu or sink or spreader) near substrate)) and (dice or singulate or singulating or cut or saw)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24
-	17	((257/758.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)) and (dice or singulate or singulating or cut or saw)) and (@ad<20011231)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24
-		438/618.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:06
-	76	(438/618.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)) and (@ad<20011231)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 14:01

-	7	((438/618.ccls. and ((metal or metallic or copper or cu or sink or spreader) near	USPAT; US-PGPUB;	2003/10/24 13:04
		substrate)) and (@ad<20011231)) and (dice or singulate or singulating or cut or	EPO; JPO; DERWENT;	
_	0	saw) 438/198.ccls. and ((metal or metallic or	<pre>IBM_TDB USPAT;</pre>	2003/10/24
		copper or cu or sink or spreader) near	US-PGPUB;	13:07
		substrate)	EPO; JPO;	
			DERWENT;	
	98	438/622.ccls. and ((metal or metallic or	IBM_TDB USPAT;	2003/10/24
-	90	copper or cu or sink or spreader) near	US-PGPUB;	13:08
		substrate)	EPO; JPO;	
			DERWENT;	
_	46	"L163" and (@ad<20011231)	IBM_TDB USPAT;	2003/10/24
_	40	LIGS and (ead\20011231)	US-PGPUB;	13:07
1	ĺ		EPO; JPO;	
			DERWENT;	
_	86	(438/622.ccls. and ((metal or metallic or	IBM_TDB USPAT;	2003/10/24
		copper or cu or sink or spreader) near	US-PGPUB;	13:08
		substrate)) and (@ad<20011231)	EPO; JPO;	
			DERWENT; IBM TDB	
1 - !	7	((438/622.ccls. and ((metal or metallic	USPAT;	2003/10/24
1	1	or copper or cu or sink or spreader) near	US-PGPUB;	13:08
	-	substrate)) and (@ad<20011231)) and (dice	EPO; JPO;	
		or singulate or singulating or cut or saw)	DERWENT; IBM TDB	
_	55		USPAT;	2003/10/24
]		copper or cu or sink or spreader) near	US-PGPUB;	13:08
		substrate)	EPO; JPO;	
			DERWENT; IBM TDB	
_	55	(438/98.ccls. and ((metal or metallic or	USPAT;	2003/10/24
		copper or cu or sink or spreader) near	US-PGPUB;	13:08
		substrate)) and (@ad<20011231)	EPO; JPO; DERWENT;	
			IBM TDB	í
-	4130	((metal or metallic or steel) near	USPĀT;	2003/10/24
		substrate) and (chips or dies)	US-PGPUB;	14:01
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	1683	(((metal or metallic or steel) near	USPAT;	2003/10/24
		substrate) and (chips or dies)) and (dice or singulate or singulating or cut or	US-PGPUB; EPO; JPO;	14:01
		saw)	DERWENT;	
			IBM_TDB	0000/10/0
-	1463	((((metal or metallic or steel) near substrate) and (chips or dies)) and (dice	USPAT; US-PGPUB;	2003/10/24
		or singulate or singulating or cut or	EPO; JPO;	45.13
		saw)) and (@ad<20011231)	DERWENT;	
<u> </u>	789	////motal or motallia as ataal) sar-	IBM_TDB	2003/10/24
-	/09	<pre>(((((metal or metallic or steel) near substrate) and (chips or dies)) and (dice</pre>	USPAT; US-PGPUB;	14:00
		or singulate or singulating or cut or	EPO; JPO;	
		saw)) and (@ad<20011231)) and (dielectric	DERWENT;	
]_	18	or insulate or insulating) ("4630096" "4714516" "4783695"	IBM_TDB USPAT	2003/10/24
		"4827328" "4835704" "4860166"	UDIAL	13:50
		"4866508" "4878991" "4884122"		
		"4894115" "4901136" "4907062" "4918811" "4933042" "5049980"		
		"5065282" "5091769" "5111278").PN.		
-	18	("4630096" "4714516" "4783695"	USPAT	2003/10/24
		"4827328" "4835704" "4860166" "4866508" "4878991" "4884122"		13:53
		"4894115" "4901136" "4907062"		
		"4918811" "4933042" "5049980"		
	L	"5065282" "5091769" "5111278").PN.	L	

-	18	("4630096" "4714516" "4783695"	USPAT	2003/10/24
		"4827328" "4835704" "4860166"		13:54
		"4866508" "4878991" "4884122"		
		"4894115" "4901136" "4907062"		
		"4918811" "4933042" "5049980"		ļ
		"5065282" "5091769" "5111278").PN.		0000 (10 (04
-	56	5250843.URPN.	USPAT	2003/10/24
				13:54
-	413	1 , ,	USPAT;	2003/10/24
1	!	and (chips or dies)	US-PGPUB;	14:01
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	/ _ / _
) -	361		USPAT;	2003/10/24
		wafer) and (chips or dies)) and	US-PGPUB;	14:01
		(@ad<20011231)	EPO; JPO;	
	1		DERWENT;	
İ			IBM_TDB	1
-	190	,,,,	USPAT;	2003/10/24
		wafer) and (chips or dies)) and	US-PGPUB;	14:02
	1	(@ad<20011231)) and (dice or singulate or	EPO; JPO;	
		singulating or cut or saw)	DERWENT;	
]	IBM_TDB	
-	124	1 , , , , ,	USPAT;	2003/10/24
}		wafer) and (chips or dies)) and	US-PGPUB;	14:02
	ļ	(@ad<20011231)) and (dice or singulate or	EPO; JPO;	
1	Ì	singulating or cut or saw)) and	DERWENT;	
L	L	(dielectric or insulate or insulating)	IBM_TDB	l